Front Matter: Volume 7661


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Introduction

On behalf of the Thermosense Steering Committee and my co-chair Morteza Safri, I would like to welcome you to the Thermosense XXXII conference proceedings. This year the conference was held over a two-day period from April 6 through April 7, 2010. The conference was held at the Orlando World Center Marriott Resort and Convention Center, Orlando, Florida, USA. This year the Thermosense conference structure consisted of five sessions: Utilities and Fluid Dynamics, Security and Surveillance, Buildings and Infrastructure, Process Monitoring, NDE and Material Evaluation. Thermosense also hosted a special session of vendor presentations followed by a reception.

Thermosense has a permanent home on the World Wide Web. Interested individuals may now view abstracts, schedules, the call for papers, conference details, committee minutes, and other Thermosense related information by pointing their browser software to http://www.thermosense.org. I expect that both the content and usefulness of this site will continue to expand in the future.

I would also like to take this opportunity to thank all of the individuals who have helped to organize and run this conference, as well as, those who have contributed by giving presentations and submitting manuscripts to these proceedings. Thermosense has greatly benefited from the hard working and dedicated staff at SPIE. In addition, no conference the size of Thermosense could succeed for 32 years without a strong and supportive Program Committee. The thermal imaging community is lucky to have such talented people give so generously of their time to assure the continued success of this conference. I also want to thank those who have agreed to take on the added responsibility of chairing the various sessions of this conference. Finally, I would like to thank last year’s chair, Douglas Burleigh, for all of his valuable advice throughout the past year.

Ralph B. Dinwiddie
Morteza Safai